IPC ASSOCIATION CONNECTION ELECTRONICS INDUSTRIES	© Copyright 2005. IP	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1					Form Type ³ Distribute	* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				als and Mf	g Informatio	on		
upplier Inform	nation								·					
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi											2024-04-20			
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			I	Phone - Representative*			Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Request	er Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	N	Ianufacturing Site	V	Veight*	UOM	Unit Type
	FDMF8811 100V Smart Po		100V Smart Power	er Stage		2024-04-20 F		PBB		51.40115	mg	Each		
	Process Informati		' 10	A.11	OTD 020 Mg1	D. C	D 1 D	D 1 T		M T (P. 1	T.	N. 1	CD CL	
2 ,			Terminal Base Alloy J-STD-020 MSI		Rating	Peak Process Body Temperatur					er of Reflow Cyc	cles		
•	in (Sn) - annealed	C	U Alloy	1			260		IC.	30	secono	ls 3		
omments														
	time at peak temperatui													
or more informat	ion regarding material c	composition j	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and everect to the best of its knowledges that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier sate as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and/Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	42.0022	mg	Supplier	Zinc (Zn)	7440-66-6		0.0504	mg
			Supplier	Iron (Fe)	7439-89-6		1.0081	mg
			Supplier	Copper (Cu)	7440-50-8		40.9101	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0336	mg
Clip Attach	0.2	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.015	mg
			Supplier	Proprietary	Proprietary Data		0.013	mg
			Supplier	Bismaleimide	13676-54-5		0.056	mg
			Supplier	PTFE	9002-84-0		0.116	mg
Die	5.4	mg	Supplier	Silicon (Si)	7440-21-3		5.4	mg
Die Attach Solder	7.60012	mg	Supplier	Silver (Ag)	7440-22-4		0.19	mg
			A	Lead (Pb)	7439-92-1	7a	7.0301	mg
			Supplier	Tin (Sn)	7440-31-5		0.38	mg
Lead Frame	51.7993	mg	Supplier	Silver (Ag)	7440-22-4		2.59	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0622	mg
			Supplier	Iron (Fe)	7439-89-6		1.2432	mg
			Supplier	Copper (Cu)	7440-50-8		47.8626	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0414	mg
Mold Compound-Black	40.1995	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.613	mg
			Supplier	Carbon Black (C)	1333-86-4		0.201	mg
			Supplier	Silica (SiO2)	14464-46-1		35.3756	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.01	mg
Plating	4.1	mg	Supplier	Tin (Sn)	7440-31-5		4.1	mg
Wire Bond	0.10003	mg	Supplier	Palladium (Pd)	7440-05-3		0.0018	mg
			Supplier	Gold (Au)	7440-57-5		0.0001	mg
			Supplier	Copper (Cu)	7440-50-8		0.0981	mg